

BRCS080N04ZB

Rev.A May.-2022



DATA SHEET



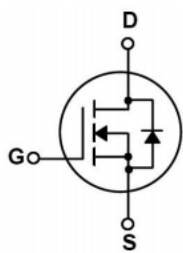
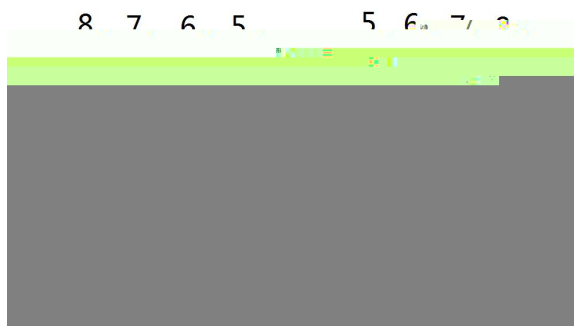
N-Channel Enhancement Mode Field Effect Transistor in a DFN3 3A-8L Plastic Package.

$$V_{DS} (V) = 40V$$

$$I_D = 40A (V_{GS} = \pm 20V)$$

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Suited for low voltage applications such as automotive, DC/DC Converters, and high efficiency switching for power management in portable and battery operated products.



/ Marking

See Marking Instructions.

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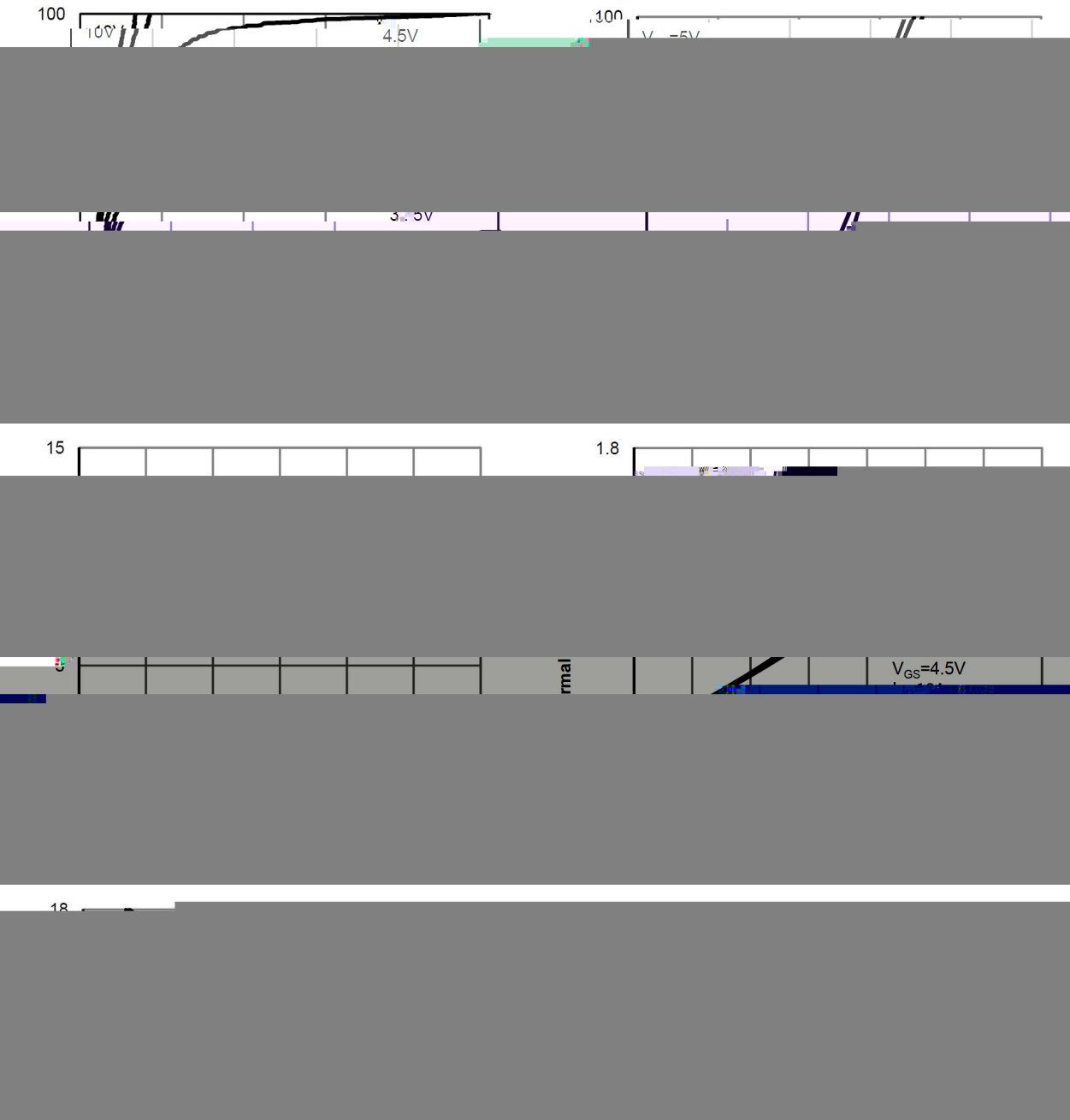


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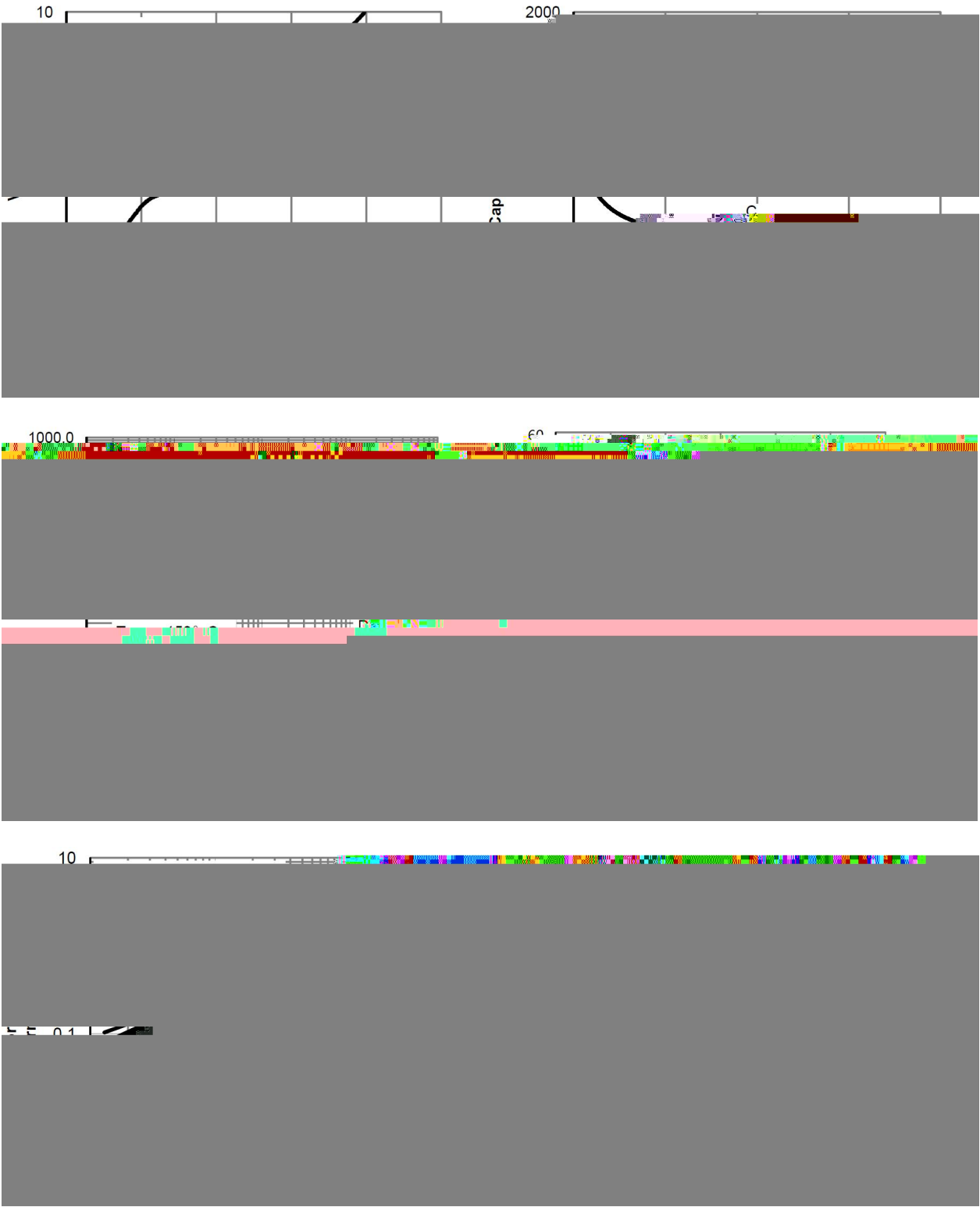
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Total Gate Charge	$Q_{g(10V)}$	$V_{DS}=20V$ $V_{GS}=4.5V$ $I_D=20A$		20		nC
Total Gate Charge	$Q_{g(4.5V)}$			8.5		
Gate-Source Charge	Q_{gs}			5.5		
Gate-Drain Charge	Q_{gd}			3		

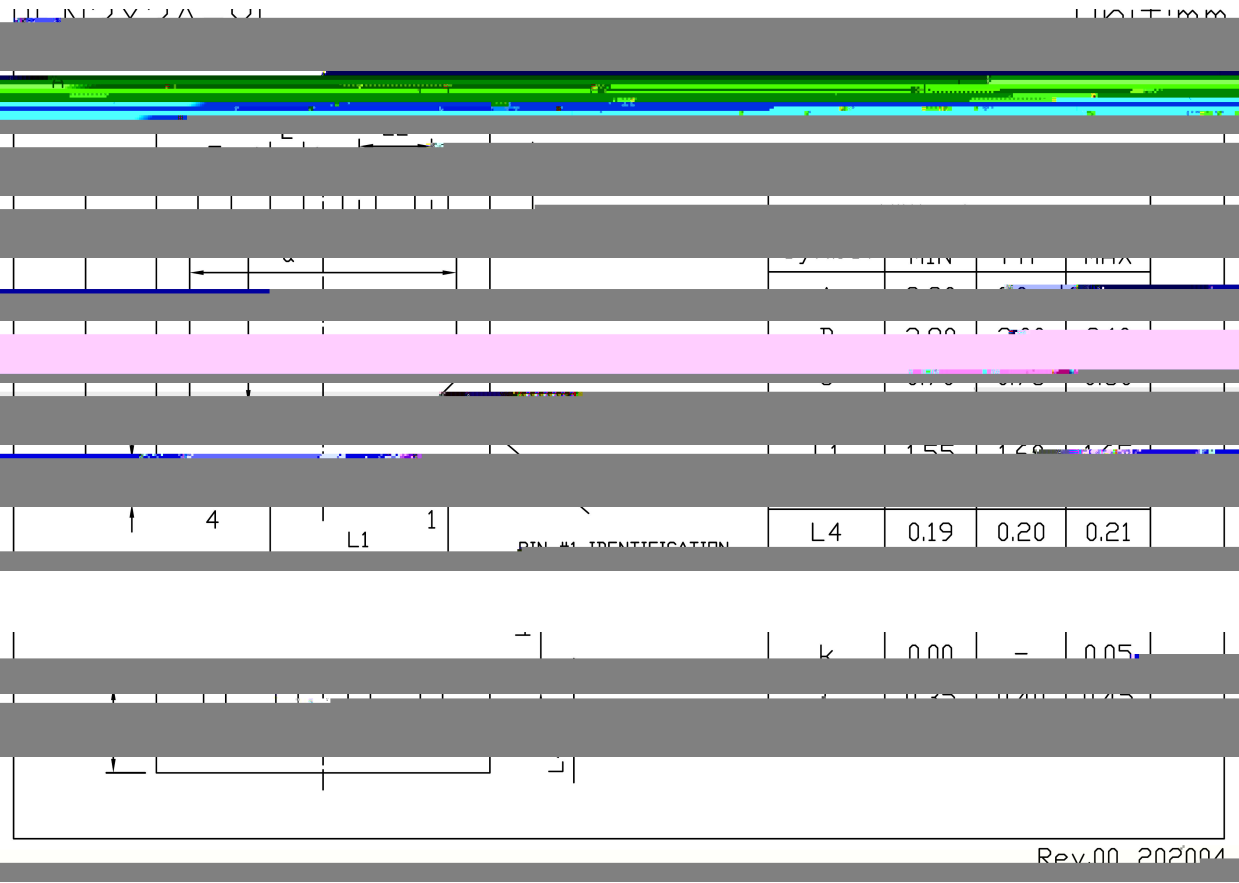
/ Electrical Characteristic Curve



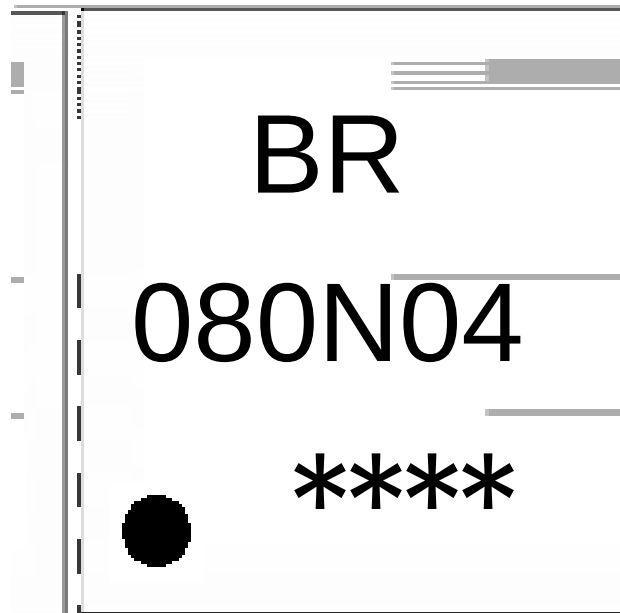
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



BR

080N04

Note:

BR: Company Code.

080N04: Product Type

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

- | | | | |
|---|---------|-----------|--|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | 2 | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C	10±1 sec.	Temp.:260±5°C	Time:10±1 sec
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/ Packaging SPEC.

/ REEL

Package Type	Units	"	#	\$	Dimension	"	%	&	(unit ' mm ³)
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